

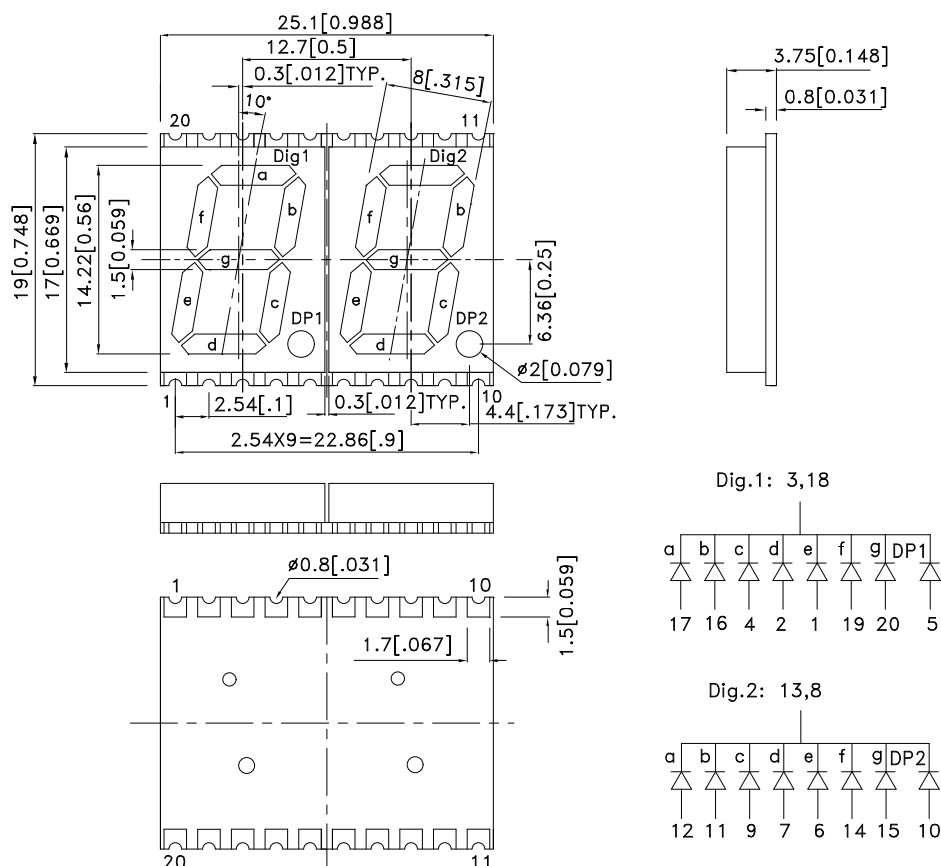
Features

- 0.56inch digit height.
- Low current operation.
- Excellent character appearance.
- Mechanically rugged.
- Gray face, white segment.
- Package: 200pcs/ reel.
- Moisture sensitivity level : level 2a.
- RoHS compliant

Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.



Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
KCDC56-123	Green (AlGaInP)	WHITE DIFFUSED	8000	35500	Common Cathode, Rt. Hand Decimal

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Green	574		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Green	570		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Green	20		nm	I _F =20mA
C	Capacitance	Green	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Green	2.1	2.5	V	I _F =20mA
I _R	Reverse Current	Green		10	uA	V _R =5V

Notes:

1.Wavelength: +/-1nm.

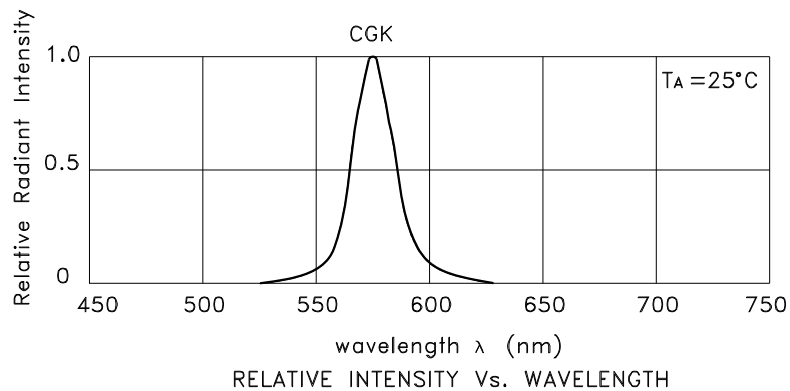
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

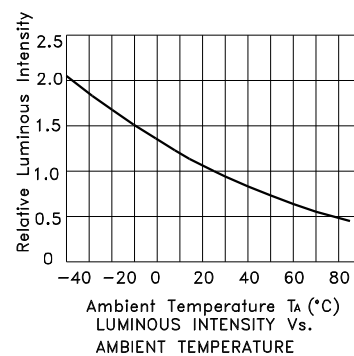
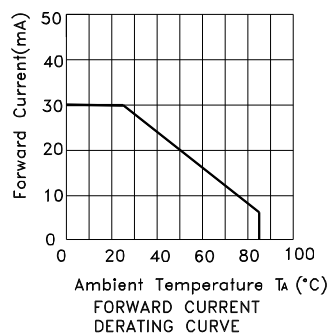
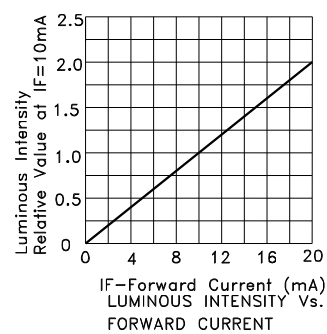
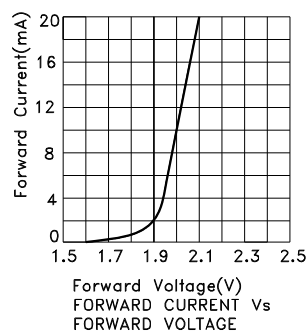
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



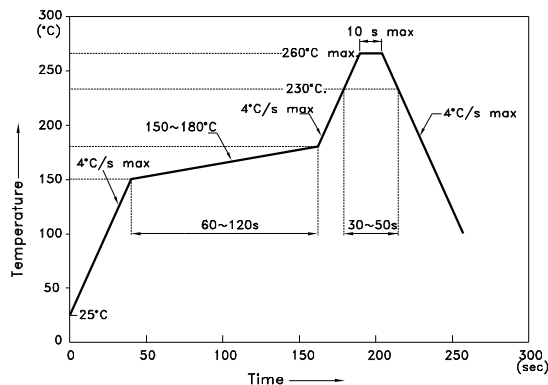
Green

KCDC56-123



KCDC56-123

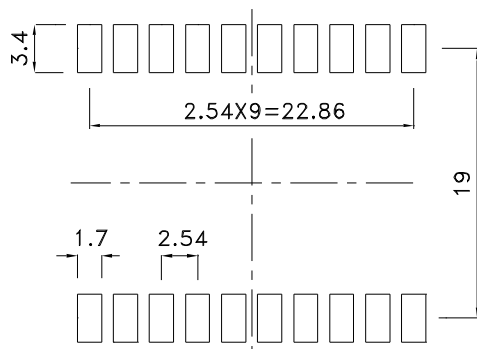
Reflow Soldering Profile For Lead-free SMT Process.



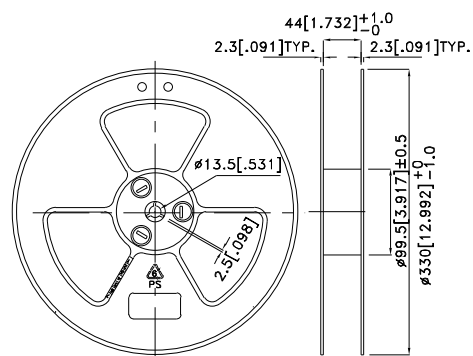
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

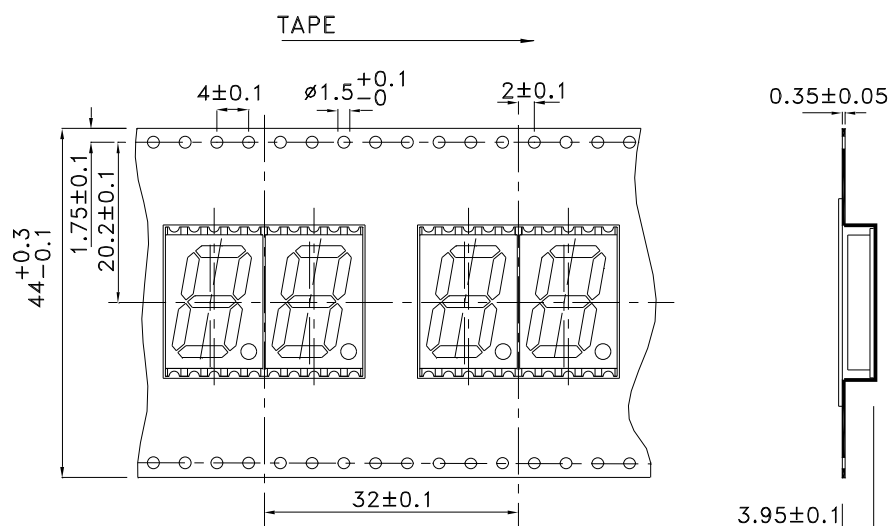
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.15)



Reel Dimension

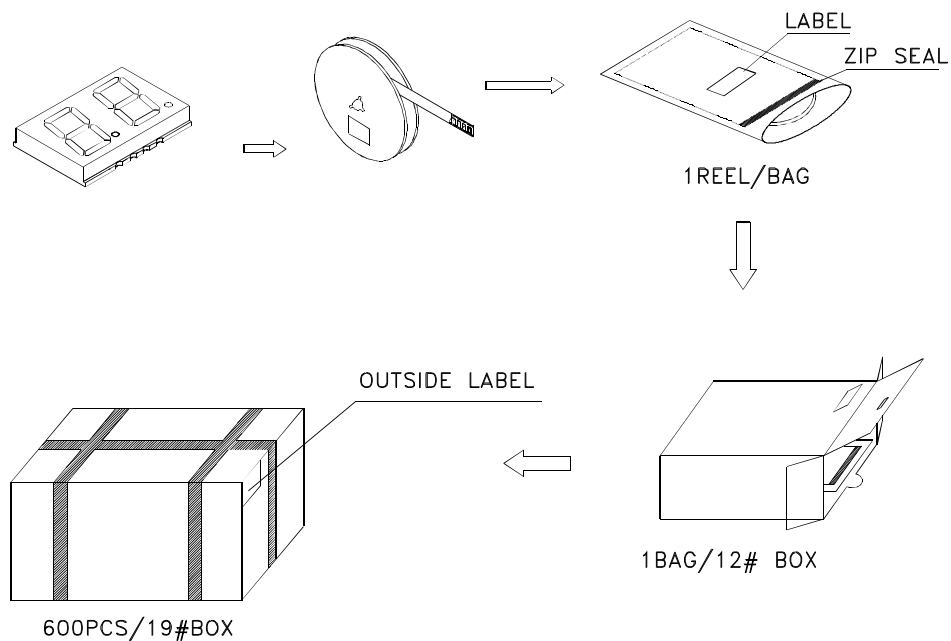


Tape Specifications (Units : mm)

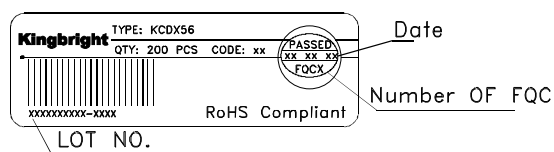


PACKING & LABEL SPECIFICATIONS

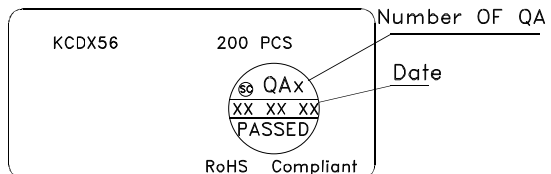
KCDC56-123



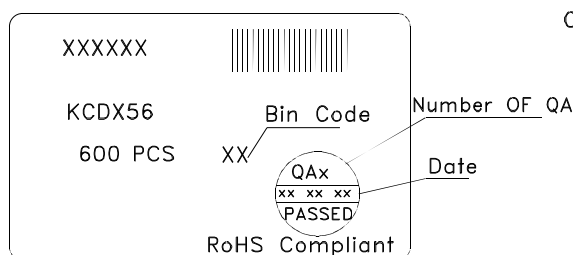
Inside LABEL Paste On The Tape



Outside LABEL Paste On The BAG



Outside LABEL Paste On The 19#Box



Outside LABEL Paste On The 12#Box

